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HARTING DIN Signal female connector RoHS compliant				Recommended configuration of plated through holes for press-in termination In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes. drilled hole Ø finished hole Ø plating (e.g. Sn) Cu min. 25 µm <table><tr><td rowspan="2">Tin plated PCB (HAL) acc. to EN 60352-5</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Sn plated hole Ø</td><td>max. 15 µm 0,94 – 1,09 mm</td></tr><tr><td rowspan="2">Chemical tin plated PCB</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Sn plated hole Ø</td><td>min. 0,8µm 1,00 – 1,10 mm</td></tr><tr><td rowspan="3">Gold /Nickel plated PCB</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Ni</td><td>3 – 7 µm</td></tr><tr><td>Au plated hole Ø</td><td>0,05 – 0,12 µm 1,00 – 1,10 mm</td></tr><tr><td rowspan="2">Silver plated PCB</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>Ag plated hole Ø</td><td>0,1 – 0,3 µm 1,00 – 1,10 mm</td></tr><tr><td rowspan="2">Copper plated PCB (OSP)</td><td>Drilled hole Ø</td><td>1,15±0,025 mm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr></table>				Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15±0,025 mm	Sn plated hole Ø	max. 15 µm 0,94 – 1,09 mm	Chemical tin plated PCB	Drilled hole Ø	1,15±0,025 mm	Sn plated hole Ø	min. 0,8µm 1,00 – 1,10 mm	Gold /Nickel plated PCB	Drilled hole Ø	1,15±0,025 mm	Ni	3 – 7 µm	Au plated hole Ø	0,05 – 0,12 µm 1,00 – 1,10 mm	Silver plated PCB	Drilled hole Ø	1,15±0,025 mm	Ag plated hole Ø	0,1 – 0,3 µm 1,00 – 1,10 mm	Copper plated PCB (OSP)	Drilled hole Ø	1,15±0,025 mm	plated hole Ø	1,00 – 1,10 mm																																																																					
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Derating diagram acc. to IEC 60512-5 (Current carrying capacity) The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals. The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature. Control and test procedures according to DIN IEC 60512-5 Electrical Load [A] Temperature [°C]				All Dimensions in mm Original Size DIN A3 Scale 1:1 Free size tol. Ref. Sub. All rights reserved Department EC PD – DE Created by LEHNERT Inspected by ZWAHR Standardisation HOFFMANN Date 2016-11-03 State Final Release DIN Signale female connector Doc-Key / ECM-Nr. 100572187/UGD/001/B 500000111021 Type DS Number 09032100001 Rev. B Page 1/1																																																																																																			
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